BLT CIRCUIT SERVICES

AN AIM SOLDER COMPANY

Nitrosol SN100SB

Lead Free, No Clean Cored Solder Wire

DESCRIPTION

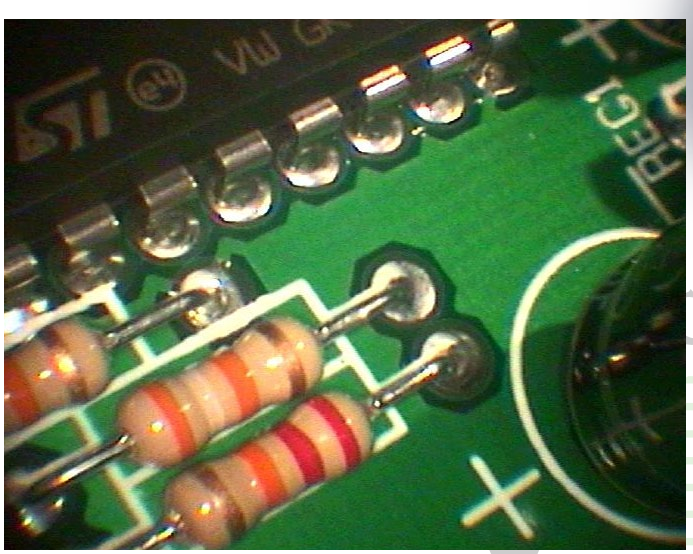
Nitrosol SN100SB *is a unique alloy and fluxing system, giving bright, shiny solder joints with a minimum amount of non-corrosive flux residue.*

Nitrosol SN100SB *has been formulated to produce very fast solder wetting, with low flux spatter and minimal fumes.*

Nitrosol SN100SB *residues are clear non-conductive, non-tacky and non-hygroscopic.*

Nitrosol SN100SB *alloy offers users a brighter solder joint than SAC alloys with considerably lower copper dissolution effect, which in turn produces a more robust and reliable solder joint.*

- Rapid wetting
- Reduced flux spatter
- Clear non-tacky residue
- Excellent joint appearance
- Low fume level
- Available in 0.25, 0.5, 0.7, 1.0 & 1.2mm diameters



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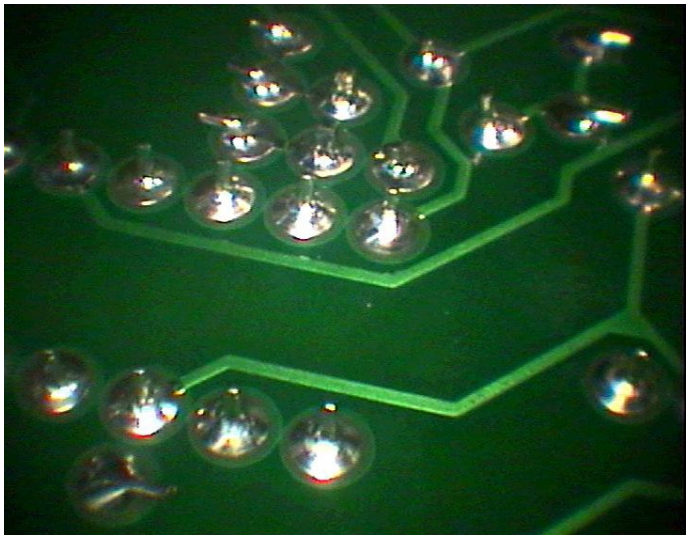
PRODUCT INFORMATION AND TECHNICAL DATA

Physical Properties

Flux Types	SD-82	NS-31
IPC J-STD-004A Classification	ROL0	ROM1*
IPC J-STD-004D Classification	ROL1	ROM1*
Flux Content	2.2 and 3.3%	3.0%

*Higher activity version



Typical Solder Analysis

Sn	99.0%	Ni	0.04%
Sb	0.22%	Fe	0.001%
Cu	0.60%	Zn	0.001%
Ag	0.07%	Al	0.0005%
Bi	0.05%	Pb	0.01%

Solder Hardness	11.870 HV (using a 1 kilo load).
Solder Melting Point	227°C

Warranty

All reasonable endeavours have been made to ensure that the information contained in this data sheet is accurate, but it is submitted on the express condition that BLT Circuit Services Ltd. shall be under no liability whatsoever in respect thereof or for any loss, injury, damage or liability of whatsoever nature arising, suffered or incurred as a consequence of its use.

Electrical Reliability

Test	Requirement	Result
JIS SIR Test (JIS-Z-3197)	1.0 x 10^{11} Ω minimum	PASS
Bellcore SIR Test (GR-78-core)	1.0 x 10^{8} Ω minimum	PASS
IPC SIR Test (J-STD-004A)	1.0 x 10^{8} Ω minimum	PASS
IPC SIR Test (J-STD-004B)	1.0 x 10^{8} Ω minimum	PASS

Chemical Reliability

Test	Requirement	Result
Copper Corrosion Test (IPC-TM-650-2.6.15)	No evidence of corrosion	PASS
Copper Mirror Test (IPC-TM-650-2.3.32)	No complete removal of copper	PASS

Application and Handling

1. *Typical solder tip temperature should be between 375°C and 450°C but should be determined to suit solder tip size and component size.*
2. *The soldering process will generate a small amount of fumes and decomposition products that must be removed from the operators area using, a local extraction system.*
3. *Do not eat or smoke when using the product and use only in a well-ventilated area.*

Alternative Alloys Available

SACP305 (SAC305 Sn96.5, Ag3, Cu0.5) and also available in 63/37 LEADED and 62/36/2 LEADED with flux content of 1.6%

Selective Solder solid wire is also available in the above alloys Please see specification below.

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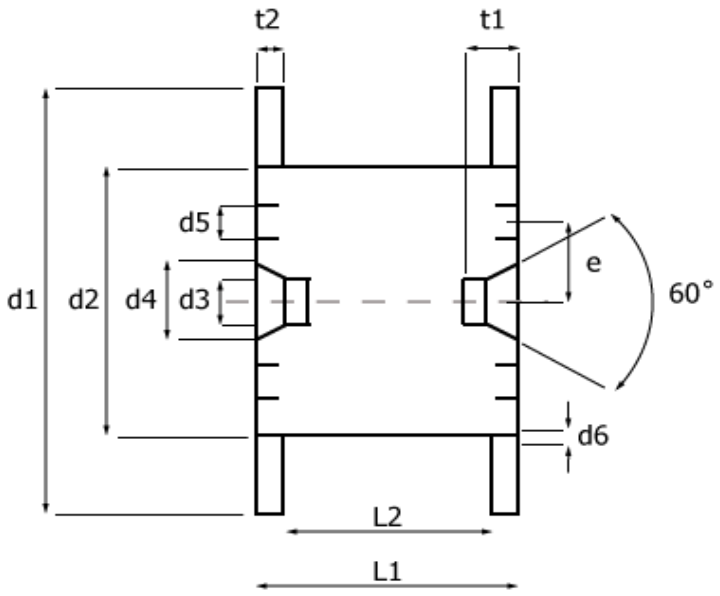
SELECTIVE SOLDER SOLID WIRE 2/3Kg REELS (DIN 125mj)



d1 =125mm
d3 = 16mm
L1 =125mm